



**Qualcomm Incorporated**

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[www.qualcomm.com](http://www.qualcomm.com)

2 November 2023

Ms. Elisabetta Comin  
Mr. Ingbert Sigovich  
ETSI, Mobile Competence Center (MCC)  
650, route des Lucioles  
Sophia-Antipolis  
France

Subject: Nomination of candidate for the 3GPP TSG RAN5 Vice Chairman

Dear Ms. Comin and Mr. Sigovich:

I am pleased to inform you that Qualcomm, through its ATIS 3GPP affiliation, is nominating Mr. Pradeep Gowda as candidate for the position of 3GPP TSG RAN5 Vice Chairman at the upcoming election in RAN5#101 (Nov-2023).

Pradeep is trained to comply with all applicable antitrust/competition laws and regulations while acting in his capacity as RAN WG5 Vice Chair.

In proposing Pradeep Gowda for the position of 3GPP TSG RAN5 Vice Chairman, Qualcomm is committed to support Pradeep in this role and to support all obligations of the Vice Chairman including time and travel commitments.

A brief curriculum vitae of Pradeep Gowda is attached as a separate document.

Best Regards,

A handwritten signature in black ink, reading "Edward G. Tiedemann, Jr.", with a stylized flourish at the end.

Edward G. Tiedemann, Jr.  
Senior Vice-President, Engineering  
Qualcomm and IEEE Fellow  
QUALCOMM Technologies, Inc.



## **Pradeep Gowda**

Pradeep is currently a Senior Director Engineering at Qualcomm Technologies, Inc. where he has been employed for more than 20 years and has been involved in RF and Layer1 conformance testing of NR, LTE, CDMA2000, WCDMA and GERAN chipsets. He has been leading RF and Layer1 system testing activities, coordinating, and planning Layer1 and RF verification activities with cross functional teams (involving Standards, Systems, SW and HW engineers).

In November 2008, he started attending TSG RAN WG5 meetings and has been actively contributing to RF and Layer1 aspects of HSPA, DC-HSDPA, LTE and NR specifications over the last 15 years. During this time, he actively contributed and enabled the completion of several RAN5 HSPA, LTE and NR Work items. In the last 6 years he has taken an active role in enabling progress of 5G-NR 3GPP RF/RRM specifications, seeding the completion of REL-15 NR RAN5 specifications, and actively facilitating the progress of new REL-16/17/18 NR conformance WI's in RAN5.

Currently Pradeep is the Vice Chairman of the TSG RAN WG5 and has completed five consecutive terms as RAN WG5 Vice Chairman. During this time, he has been chairing the RF/RRM sessions in his role as RAN5 RF/RRM Subgroup Convener.

Pradeep graduated in 2001 with a master's degree in electrical engineering from State University of New York Buffalo, USA.